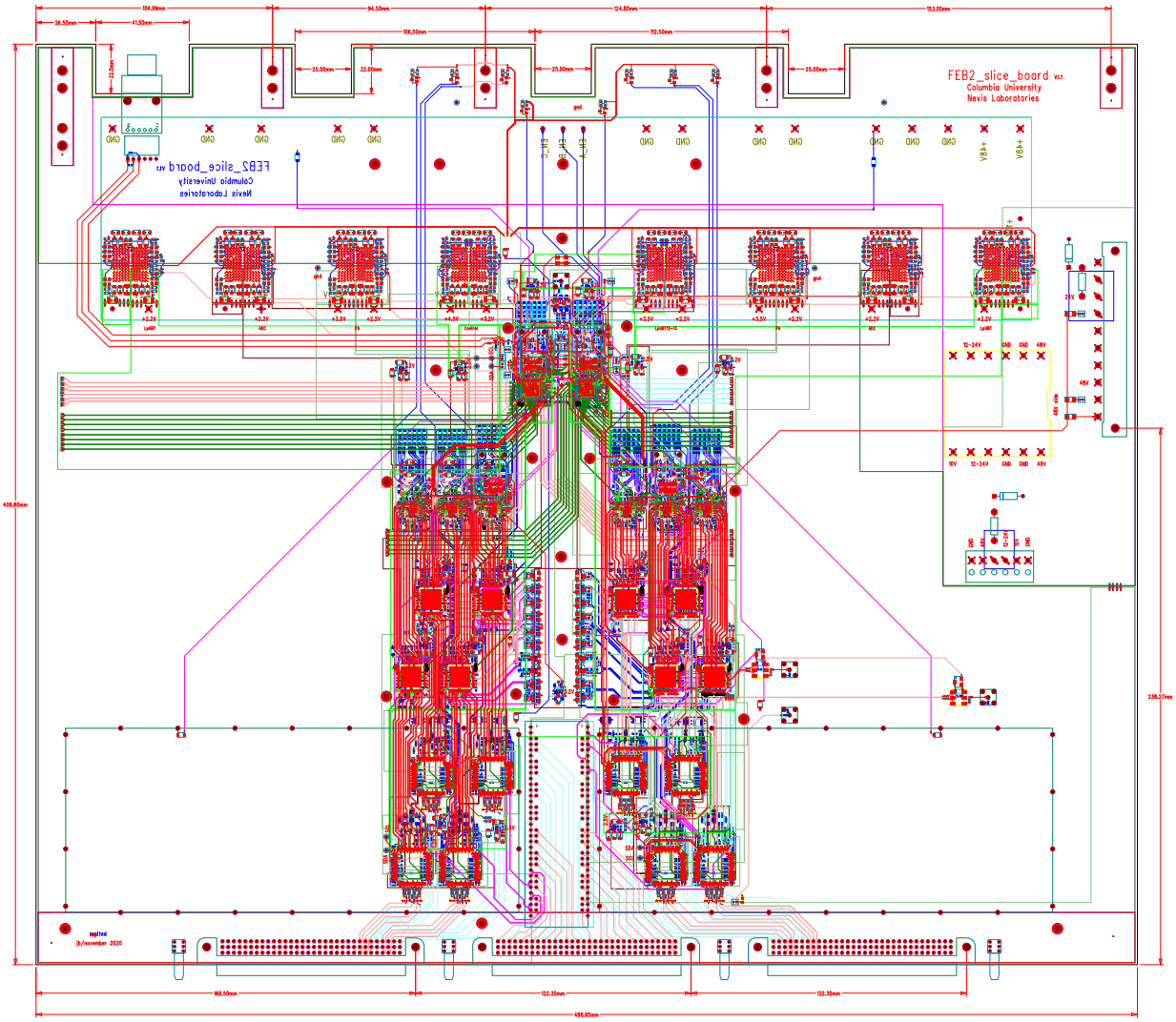

Fabrication drawing for FEB2_slice_board .
Board version: 1.2
Material EM-888K
Finish - Immersion gold
Use tolerance of +-0.08" for hole-to-edge dimensions.
Thieving allowed

The drill diameters for component holes are finished hole diameters
Exposed paddle on the underside of some chips,
vias should be under 15mil.

Build inner board corners with 0.8mm radius
Build outer board corners with 1.0mm radius

Standard route tolerance +-5mils.

Use standard green solder mask.

Use standard tolerances for hole sizes.
Board stack-up in the file Proposed-stackup.pdf.